

GAL22CV10-10 24-Pin Generic Array Logic Family

General Description

The EECMOS GAL22CV10 devices are fabricated using electrically erasable floating gate technology. This programmable memory technology applied to array logic provides designers with reconfigurable logic and bipolar performance at significantly reduced power levels.

The 24-pin GAL22CV10 features 10 programmable Output Logic Macrocells (OLMCs) allowing each TRI-STATE® output to be configured by the user. The GAL22CV10 is also capable of emulating most popular 24-pin PAL® devices.

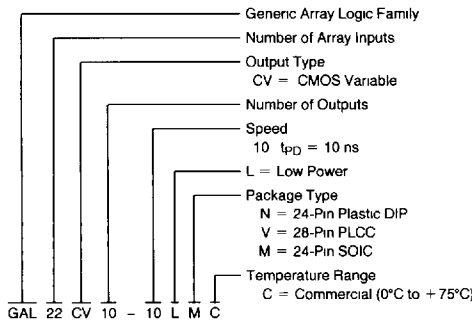
Programming is accomplished using popular hardware and software tools. NSC guarantees a minimum of 100 erase/write cycles.

Unique test circuitry and reprogrammable cells allow complete AC, DC, cell, and functionality testing during manufacture. Therefore, NSC guarantees 100% field programmability and functionality of NSC GAL® devices. In addition, a security circuit is built-in, providing proprietary designs with copy protection.

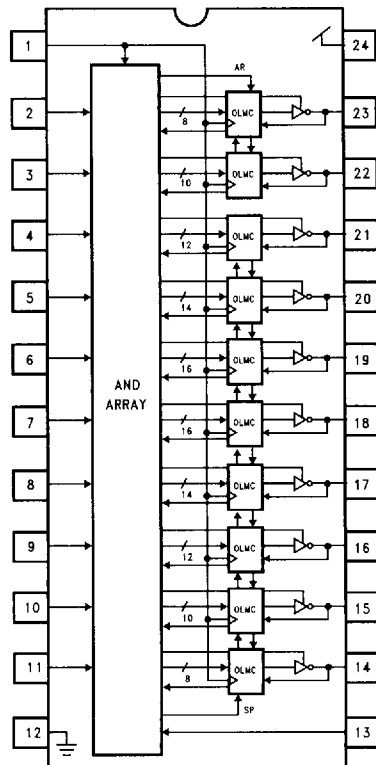
Features

- High performance EECMOS technology
 - 10 ns maximum propagation delay
 - 6 ns setup time delay
 - TTL compatible 16 mA outputs
 - 2000V ESD protection
- Reduced power
 - I_{CC} max = 130 mA @ 25 MHz
- Electrically erasable cell technology
 - Reconfigurable logic
 - 100% tested at manufacture
- Output Logic Macrocells (OLMCs)
 - Maximum flexibility for complex logic design
 - Programmable output polarity
 - Emulates popular PAL devices
- Fully supported by National OPAL™ and OPALjr development software as well as 3rd-party PLD development tools
- Security cell prevents copying logic

Ordering Information



Block Diagram



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 OPAL™ is a trademark of National Semiconductor Corporation
 GAL® is a registered trademark of Lattice Semiconductor
 PAL® is a registered trademark of and used under license from AMD Inc

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Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC}) (Note 2)	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to $V_{CC} + 0.6V$
Off-State Output Voltage (Note 2)	-0.5V to $V_{CC} + 0.6V$
Output Current	± 100 mA
Storage Temperature	-65°C to +150°C

Lead Temperature (Soldering, 10 seconds)	300°C
ESD Tolerance	2000V
$C_{ZAP} = 100$ pF	
$R_{ZAP} = 1500\Omega$	
Test Method: Human Body Model	
Test spec.: NSC SOP-5-028	

Recommended Operating Conditions

Symbol	Parameter	Commercial			Units
		Min	Typ	Max	
V_{CC}	Supply Voltage	4.75	5	5.25	V
T_A	Operating Free-Air Temperature	0	25	75	°C
t_r	Clock Rise Time			250	ns
t_f	Clock Fall Time			250	ns
$t_{rV_{CC}}$	V_{CC} Rise Time			250	ms

Electrical Characteristics

Symbol	Parameter	Conditions	Commercial		Units
			Min	Max	
V_{IH}	High Level Input Voltage		2.0	$V_{CC} + 0.3$	V
V_{IL}	Low Level Input Voltage		-0.3	0.8	V
V_{OH}	High Level Output Voltage	$V_{CC} = \text{Min}, I_{OH} = -3.2$ mA	2.4		V
V_{OL}	Low Level Output Voltage	$V_{CC} = \text{Min}, I_{OL} = 16$ mA		0.5	V
I_{OS}	Output Short Circuit Current	$V_{CC} = 5.0V, V_O = 0.5V, T_A = 25^\circ C$ (One output, duration < 1 sec.)	-30	-135	mA
C_I	Input Capacitance	$V_{CC} = 5.0V, T_A = 25^\circ C, f = 25$ MHz		6	pF
$C_{I/O}$	I/O Capacitance	$V_{CC} = 5.0V, T_A = 25^\circ C, f = 25$ MHz		12	pF

Note 1: Absolute maximum ratings are those values beyond which the device may be permanently damaged. Proper operation is not guaranteed outside the specified recommended operating conditions

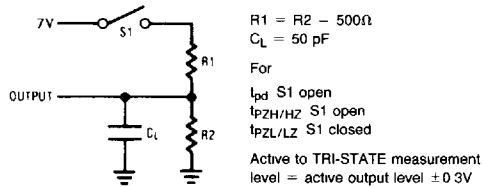
Note 2: Some device pins may be raised above these limits during programming and preload operations according to the applicable specification

AC Specifications

Symbol	Parameter	Conditions (Note 3)	Commercial		Units
			GAL22CV10-10L		
			Min	Max	
t_{PD}	Input or F/B to Combinatorial Output	S1 Open, $C_L = 50$ pF		10	ns
t_{SU}	Input or F/B Setup Time before Clock			6	ns
t_H	Hold Time (Input after Clock)			0	ns
t_{CLK}	Clock to Registered Output or F/B	S1 Open, $C_L = 50$ pF		8	ns
t_{CFB}	Clock to Registered F/B	S1 Open, $C_L = 50$ pF		7	ns
f_{MAX}	Clock Frequency	With Feedback Without Feedback	71 125		MHz
t_W	Clock Pulse Width (High/Low)	Referenced at 10% and 90%	4		ns
t_{CYCLE}	Clock Period (with F/B)	$t_{CYCLE} = t_{SU} + t_{CLK}$	12		ns
$t_{PZH/L}$	Input to Output Enable	$C_L = 50$ pF		10	ns
$t_{PZL/LZ}$	Input to Output Disable	$C_L = 50$ pF		11	ns
t_{AP}	Input to Asynchronous Reset			13	ns
t_{AR}	Asynchronous Reset Recovery Time			9	ns
t_{RESET}	Power-Up to Registered Output High	S1 Open, $C_L = 50$ pF		7.5	μ s
I_{CC}	Supply Current	$f = 25$ MHz, $V_{CC} = \text{max}$, No Load		130	mA

Note 3: See AC test load

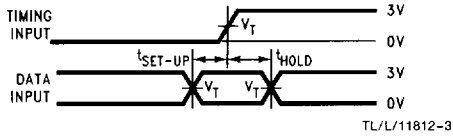
AC Test Load



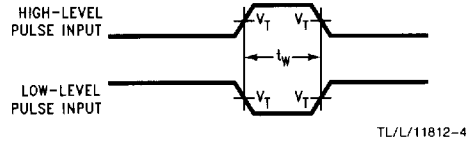
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Test Waveforms

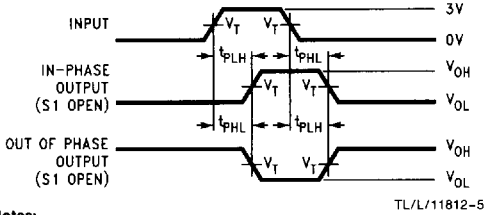
Setup and Hold



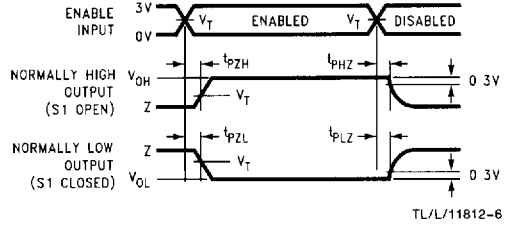
Pulse Width



Propagation Delay



Enable and Disable



Notes:

C_L includes probe and jig capacitance

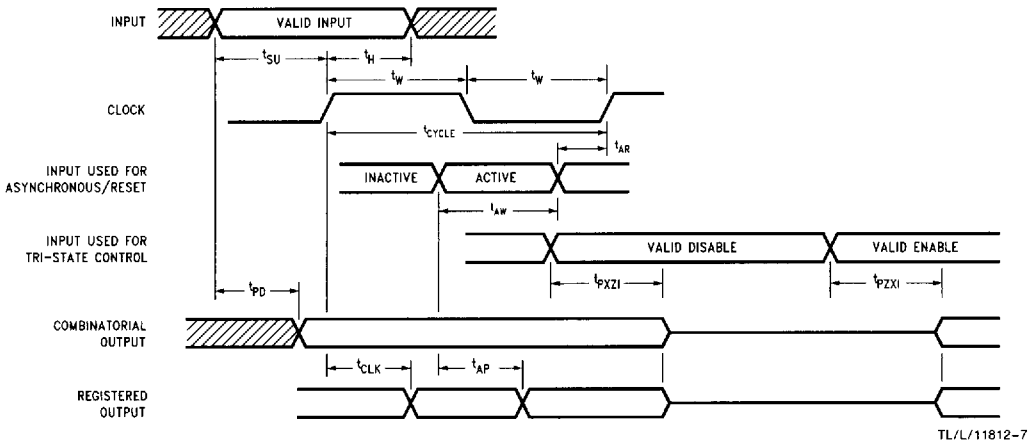
$V_T = 1.5V$

$V_{TZ} = \text{active output level } \pm 0.3V$

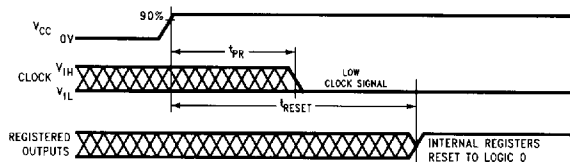
Test inputs have rise and fall times of 3 ns 10%–90%

In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily

Switching Waveform



Power-Up Reset Waveform



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Functional Description

The GAL22CV10 logic array consists of a programmable AND array with fixed OR-gate connections, similar to the traditional bipolar PAL architecture. The logic array is organized as 22 complementary input lines crossing 132 "product term" lines with a programmable EEPROM cell at each intersection (5808 cells). Each programmable cell may establish a connection between an input line (true or complement phase of an array input signal) and a product term. A product term is satisfied (logically true) when all of the input lines "connected" to it are in the high logic state.

Of the 132 product terms, 130 are distributed among ten "output logic macrocells" (OLMCs) with a varying number of terms allocated to each OLMC. For a given OLMC, 8, 10, 12, 14, or 16 product terms feed into an OR-gate to produce each output value. This varied distribution of product terms among outputs allows more optimum use of device resources. One additional product term in each of the additional OLMCs is used to control the associated TRI-STATE device output. One global product term is used to control an asynchronous reset and another global product term controls a synchronous preset.

Under control of an OLMC, each output may be designated either registered or combinational (non-registered). In the registered output configuration, the logic function output passes through a D-type flip-flop triggered by the rising edge of the clock input. Additionally, the logic function's output polarity may be designated active-high or active-low. OLMC options such as these are selected by a set of programmable architecture control EEPROM cells. These cells are normally configured automatically by the development software or programming hardware.

The four possible output configurations of each OLMC are: registered active-high, registered-active-low, combinational active-high, and combinational active-low. The registered

configurations include an internal feedback path taken directly from the register output. The combinational configurations include feedback from the I/O pin, thus allowing for bidirectional I/O or additional input channels.

All registers in a GAL22CV10 device are reset to the low state upon powering up. Outputs, in turn, assume either low or high logic levels depending on the selected output polarity. Power-up reset may simplify sequential circuit design and test by initializing the device to a known state. To ensure successful power-up reset, V_{CC} must rise monotonically until the specified operating voltage is attained.

The GAL22CV10 includes a programmable security EEPROM cell which, once programmed, prevents unauthorized reading or copying of designs programmed into the device.

Programmable Preset and Reset

The ten macrocell flip-flops share common programmable preset and reset control for easy system initialization. The Q outputs of the register will go to the logic high state following a low-to-high transition of the clock input when the synchronous preset (SP) product term is asserted. The register will be forced to the logic low state independent of the clock when the asynchronous reset (AR) product term is asserted. Product term control allows preset and reset to be functions of any combination of device inputs and output feedback. The outputs will be high or low depending upon the polarity option chosen.

Note that preset and reset control the flip-flop, not the output. Thus, if active low polarity is selected, a synchronous preset would produce low-level outputs, and an asynchronous reset would produce high-level outputs (if enabled).

GAL22CV10 Block Diagram—DIP and SOIC Connections

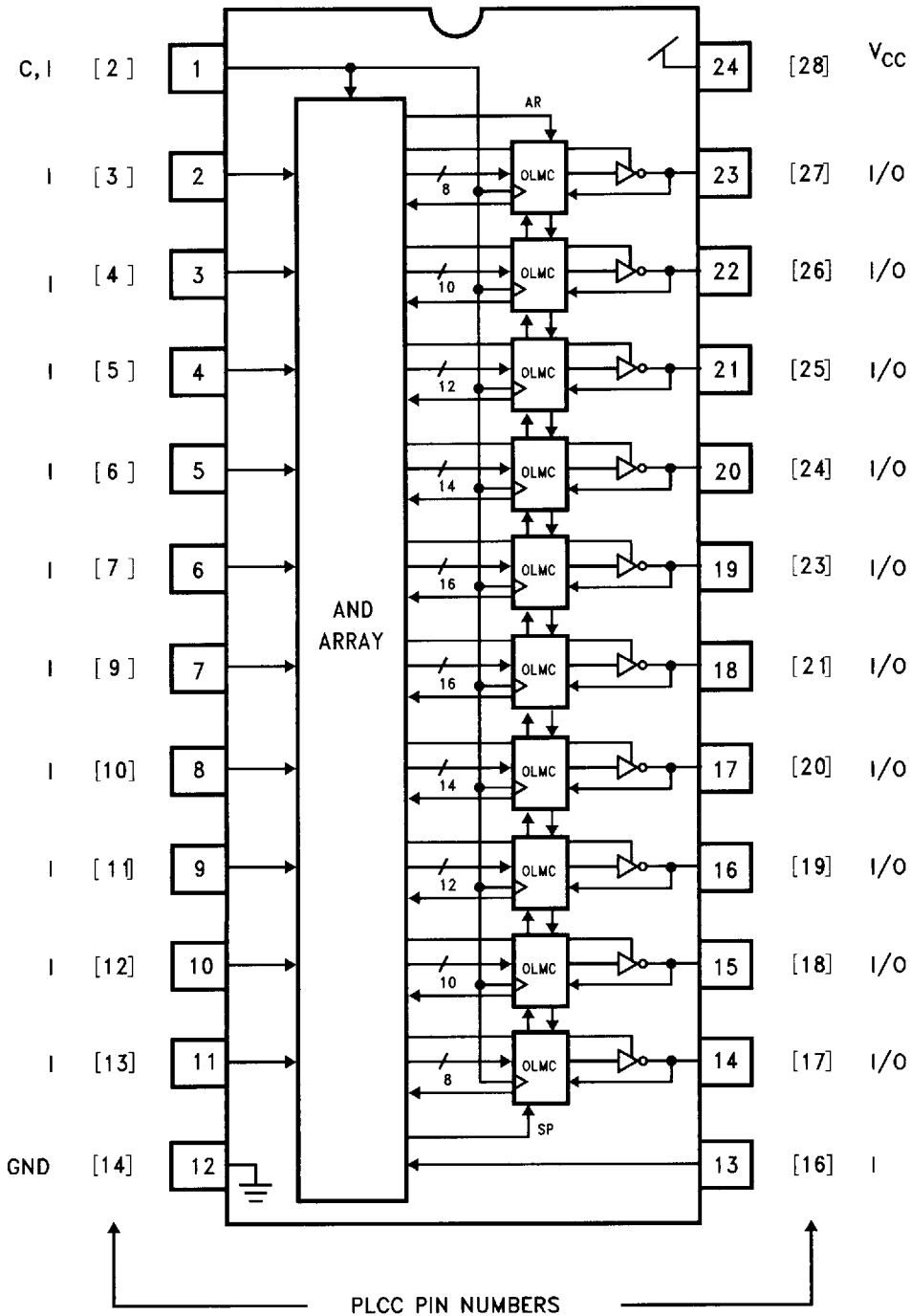
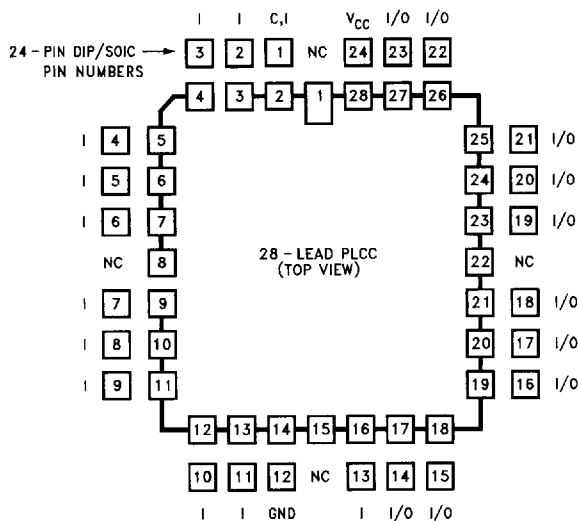


FIGURE 1

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28-Lead PLCC Connection Diagram



TL/L/11812-10

FIGURE 2

Clock/Input Frequency Specifications

The clock frequency (f_{CLK}) parameter listed in the AC Specifications table specifies the maximum speed at which the GAL22CV10 registers are guaranteed to operate. Clock frequency is defined differently for the two cases in which register feedback is used versus when it is not. In a data-path type application, when the logic functions fed into the registers are not dependent on register feedback from the previous cycle (i.e. based only on external inputs), the minimum required cycle period (f_{CLK}^{-1} without feedback) is defined as the greater of the minimum clock period (t_w high + t_w low) and the minimum "data window" period ($t_{SU} + t_H$). This assumes optimal alignment between data inputs and the clock input. In sequential logic applications such as state machines, the minimum required cycle period ($t_{CYCLE} = f_{CLK}^{-1}$ with feedback) is defined as $t_{CLK} + t_{SU}$. This provides sufficient time for outputs from the registers to feed back through the logic array and set up on the inputs to the registers before the end of each cycle.

Design Development Support

A variety of software tools and programming equipment are available to support the development of designs using GAL22CV10 products. Typical software packages, including National's OPAL software, accept Boolean logic equations to define desired functions. Most are available to run on personal computers and generate a JEDEC-compatible "cell-map" (analogous to a PAL "fuse-map"). The industry-standard JEDEC format ensures that the resulting cell-map file can be down-loaded into industry standard programming equipment.

National strongly recommends using only approved programming hardware. Programming using unapproved equipment generally voids all guarantees.

The GAL22CV10 can accept fuse-maps prepared for other PAL22V10 devices. PAL22V10 fuse-maps can be created by any JEDEC-compatible PAL development software or by loading the fuse pattern from an existing programmed PAL22V10 device into the programming unit (provided the PAL device has not been secured).

Detailed logic diagrams showing all JEDEC cell-map addresses in the GAL22CV10 logic array and OLMC are provided for direct map editing and diagnostic purposes. *Figures 3 and 4* show details of the OLMC and the programmable architecture cell combinations. *Figure 5* shows the JEDEC logic diagram and details of all programmable cell locations. For a list of current software and programming support tools available for these devices, please contact your local National sales representative or distributor.

Security Cell

A security cell is provided on all GAL22CV10 devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, the circuitry enabling array access is disabled, preventing further programming or verification of the array. The security cell can be erased only in conjunction with the array during a bulk erase cycle, so the original configuration can never be examined once this cell is programmed.

Bulk Erase

The programming equipment automatically performs a bulk erase operation prior to each programming operation. No special erase operation need be performed by the user. Bulk erase clears the logic array, architecture cells and security cell. The GAL device is thereby reverted back to its virgin state.

Manufacturer Testing

Because of EECMOS technology, GAL devices can be re-programmed. This allows each device to be completely tested by the manufacturer using numerous logic array and architecture patterns prior to shipping. Every programmable

cell and every logic path through every device is fully tested for programmability, functionality and performance to all AC and DC parameters. The customer can therefore expect 100% programming and functional yield and 100% compliance of all GAL products to datasheet specifications.

OLMC Logic Diagram

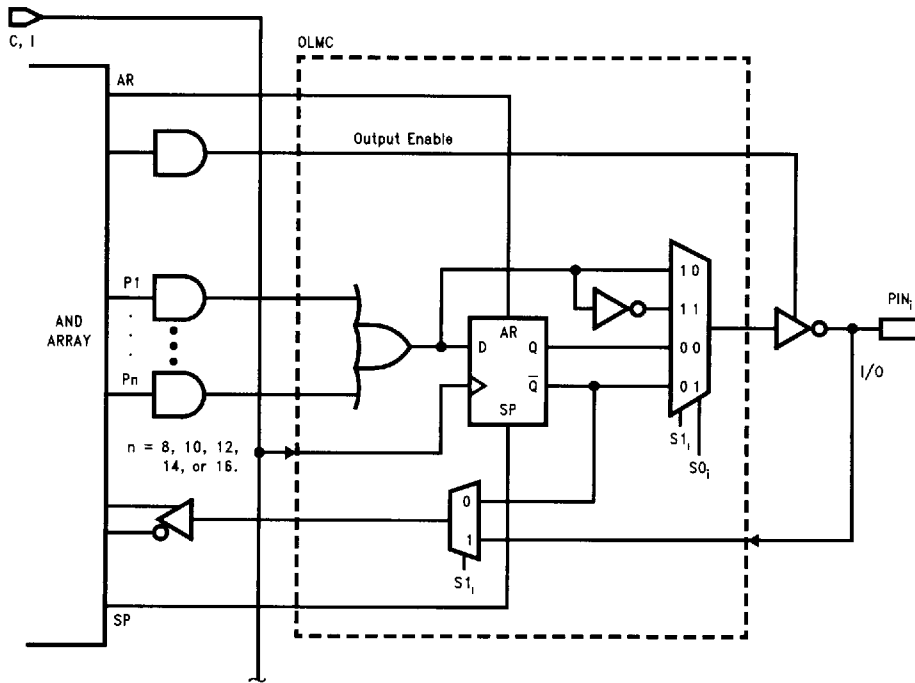


FIGURE 3

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TABLE I

S1	S0	Output Configuration
0	0	Registered/Active Low
0	1	Registered/Active High
1	0	Combinatorial/Active Low
1	1	Combinatorial/Active High

OLMC Selection Table

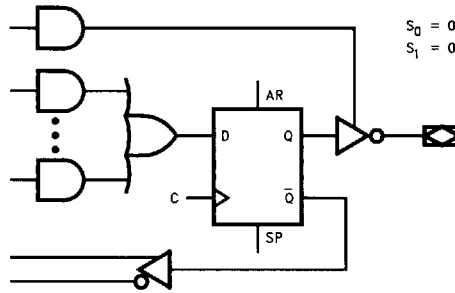


FIGURE 4-1. Registered/Active Low

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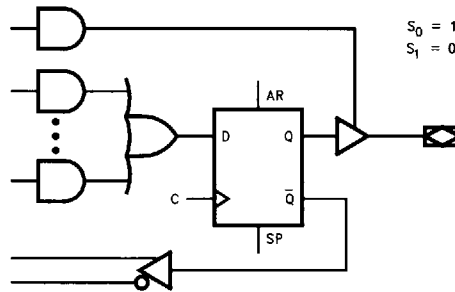


FIGURE 4-2. Registered/Active High

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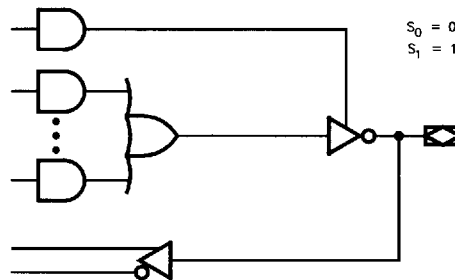


FIGURE 4-3. Combinatorial/Active Low

TL/L/11812-13

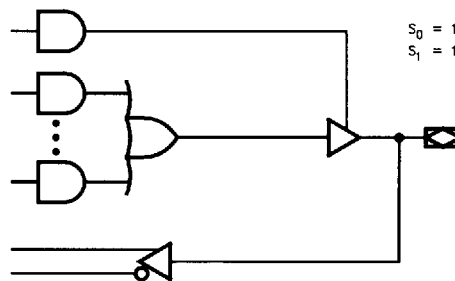
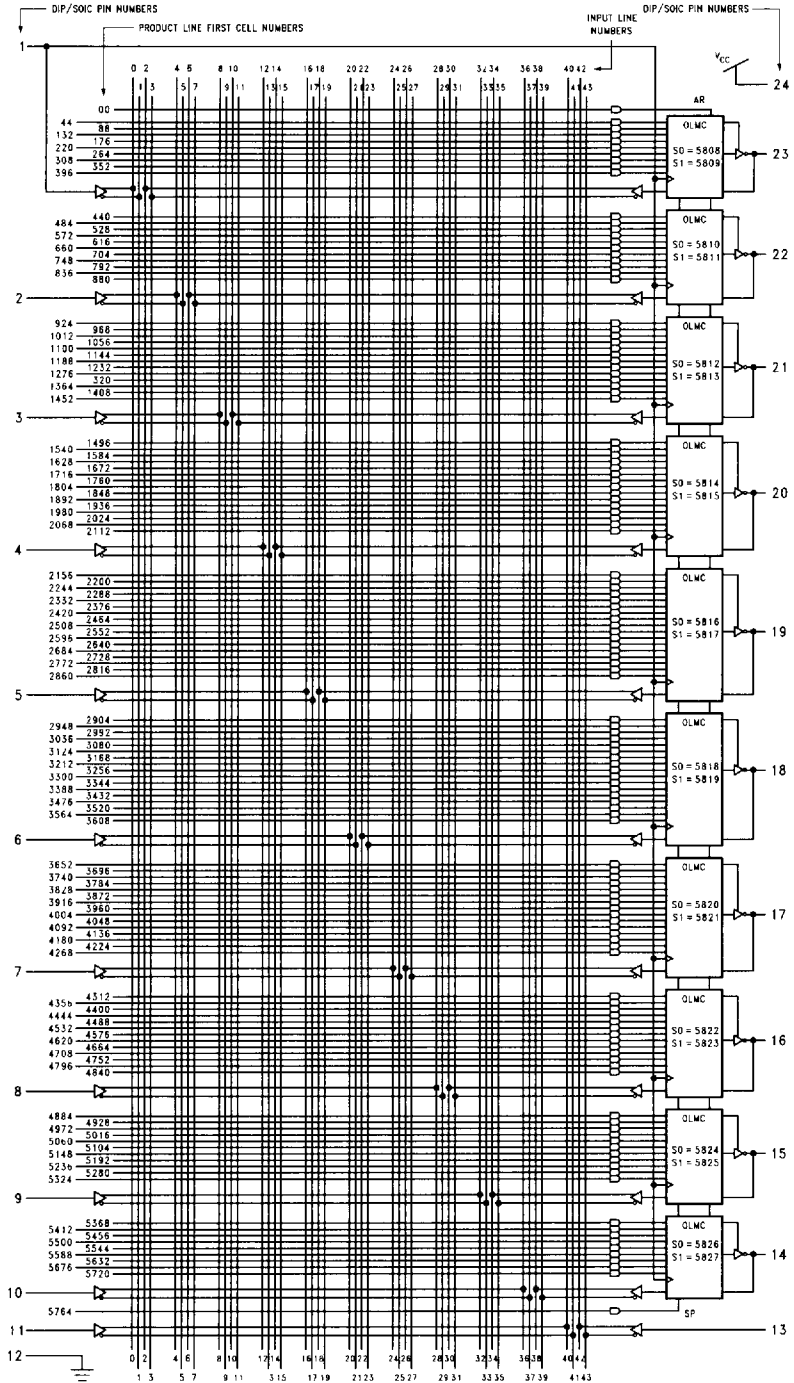


FIGURE 4-4. Combinatorial/Active High

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GAL22CV10 Logic Diagram

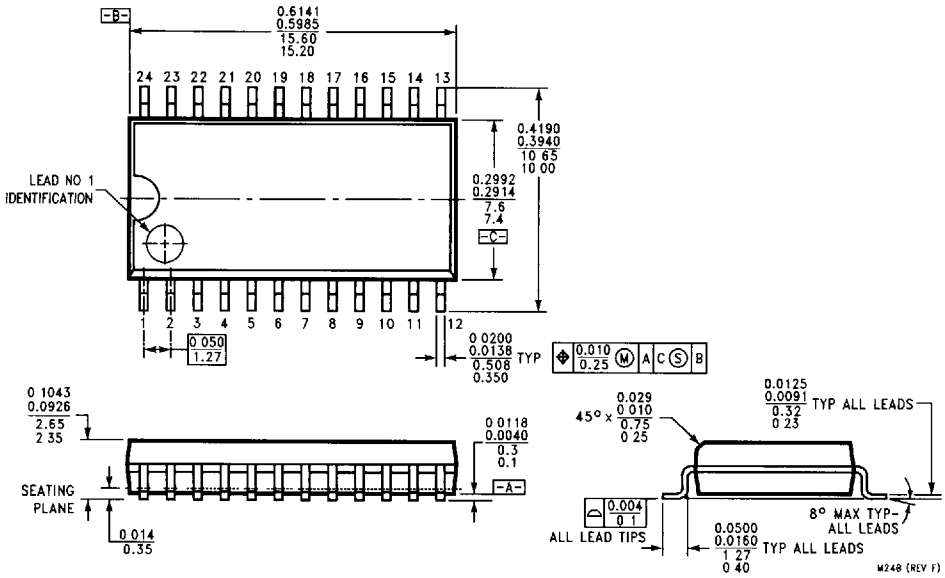


JEDEC Logic Array Cell Numbers = Product Line First Cell Number + Input Line Numbers

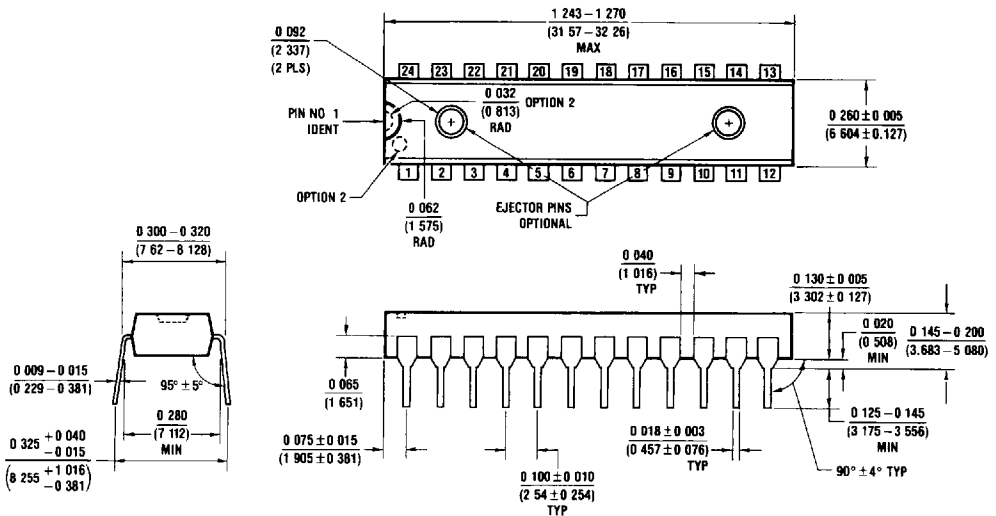
FIGURE 5

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Physical Dimensions inches (millimeters) (Continued)

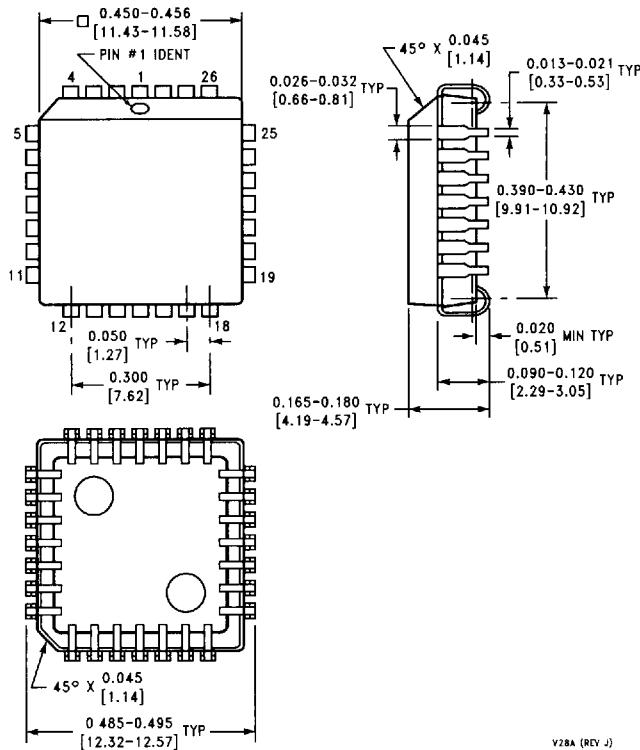


24-Lead Small Outline Integrated Circuit (SOIC) (M)
NS Package Number M24B



24-Lead Narrow Plastic Dual-In-Line Package (N)
NS Package Number N24C

Physical Dimensions inches (millimeters) (Continued)



V28A (REV J)

**28-Lead Plastic Chip Carrier (V)
NS Package Number V28A**

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